

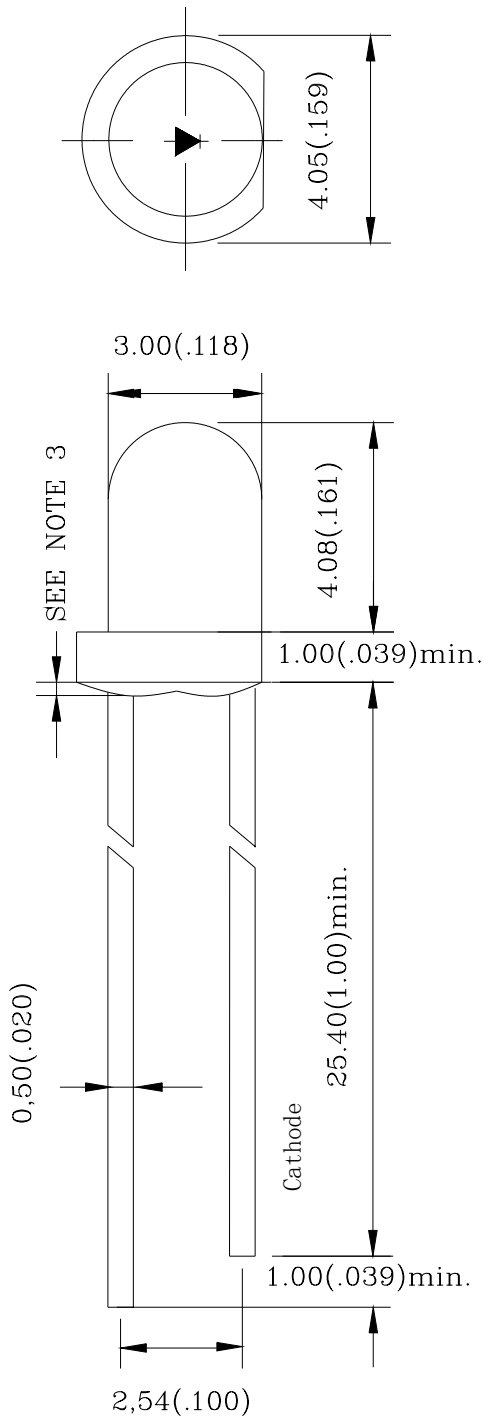


PARA LIGHT ELECTRONICS CO., LTD.
4F, No.1, Lane 93, Chien Yi Road, Chung Ho City, Taipei, Taiwan, R.O.C.

DATA SHEET

PART NO. : L34F3BT

PACKAGE DIMENSIONS



Note:

- 1.All Dimensions are in millimeters.
- 2.Tolerance is $\pm 0.25\text{mm}(0.010 \text{ "})$ Unless otherwise specified.
- 3.Protruded resin under flange is $1.5\text{mm}(0.059 \text{ "})$ max.
- 4.Lead spacing is measured where the leads emerge from the package.
- 5.Specification are subject to change without notice



3.0 mm INFRARED EMITTING DIODE

L34F3BT

FEATURES

- * EXTRA HIGH RADIANT POWER AND RADIANT INTENSITY
- * LOW FORWARD VOLTAGE
- * SUITABLE FOR HIGH PULSE CURRENT OPERATION INTENSITY
- * HIGH RELIABILITY
- * Pb FREE PRODUCTS

CHIP MATERIALS

- * Dice Material : GaAlAs/GaAs
- * Lens Color : BLUE TRANSPARENT

ABSOLUTE MAXIMUM RATING : (Ta = 25°C)

SYMBOL	PARAMETER	INFRARED	UNIT
PD	Power Dissipation	180	mW
VR	Reverse Voltage	5	V
IF	Average Forward Current	100	mA
IPF	Peak forward current (F=1KHZ,duty=0.1)	800	mA
Topr	Operating Temperature Range	-35°C to 85°C	
Tstg	Storage Temperature Range	-35°C to 85°C	

Lead Soldering Temperature { 1.6mm(0.063 inch) From Body } 260°C ± 5°C for 5 Seconds

ELECTRO-OPTICAL CHARACTERISTICS : (Ta = 25°C)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VF	Forward Voltage	IF = 20mA IF = 100mA		1.3 1.5	1.8	V
VFP	Peak Forward Voltage	IPF=800mA		2.2	2.5	V
IR	Reverse Current	VR = 5V			10	µA
λP	Peak Emission Wavelength	IF = 20mA		940		nm
2θ1/2	Half Intensity Angle	IF = 20mA		25		deg
IE	Radiant Intensity	IF = 20mA IF=100mA		10 50		mw/sr

